

HD74LS247

BCD-to-Seven-Segment Decoder / Driver (with three-state outputs)

REJ03D0465-0300

Rev.3.00

Jul.15.2005

The HD74LS247 is electrically and functionally identical to the HD74LS47, respectively, and has the same pin assignments as its equivalents.

It can be used interchangeably in present or future designs to offer designers a choice between two indicator fonts. The HD74LS47 composes the 6 and the 9 without tails and the HD74LS247 composes the 6 and the 9 with tails. Composition of all other characters, including display patterns for BCD inputs above nine, is identical. The HD74LS247 features active-low outputs designed for driving indicators directly. All of the circuits have full ripple-blanking input / output controls and a lamp test input.

Segment identification and resultant displays are shown below. Display patterns for BCD input conditions. This circuit incorporates automatic leading and / or trailing-edge zero-blanking control (RBI and RBO). Lamp test (LT) of this type may be performed at any time when the BI / RBO node is at a high level.

This type contains an overriding blanking input (BI) which can be used to control the lamp intensity by pulsing or to inhibit the outputs.

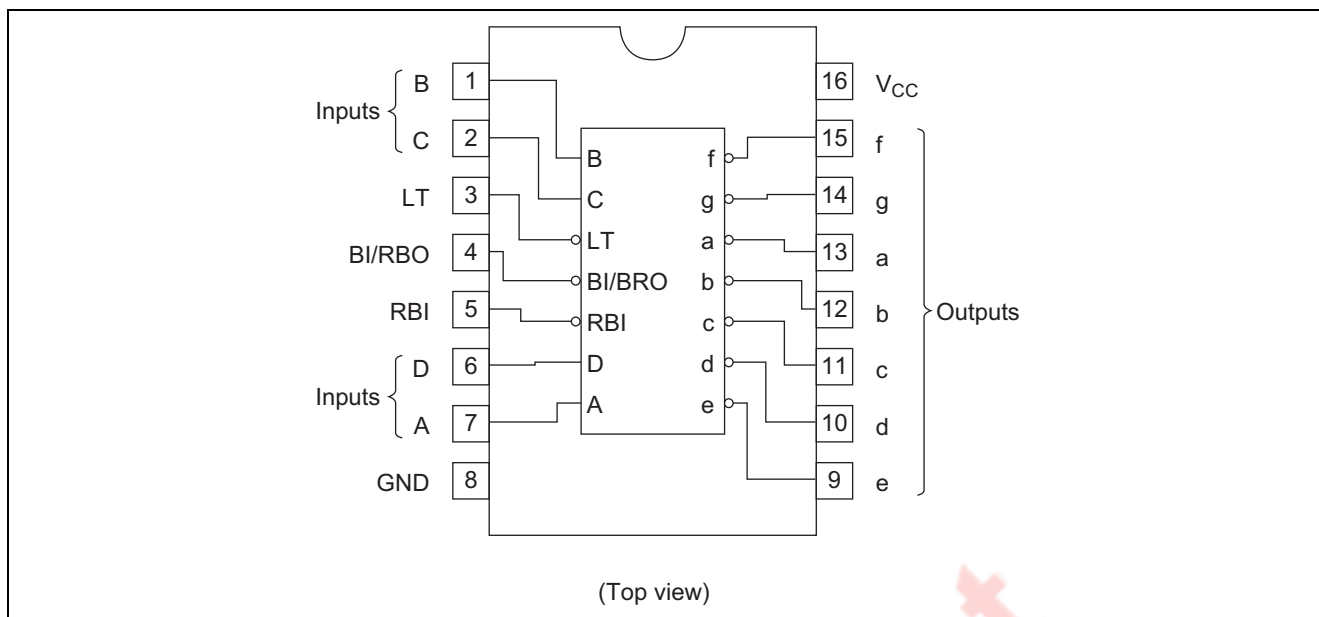
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS247P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74LS247FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74LS247RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



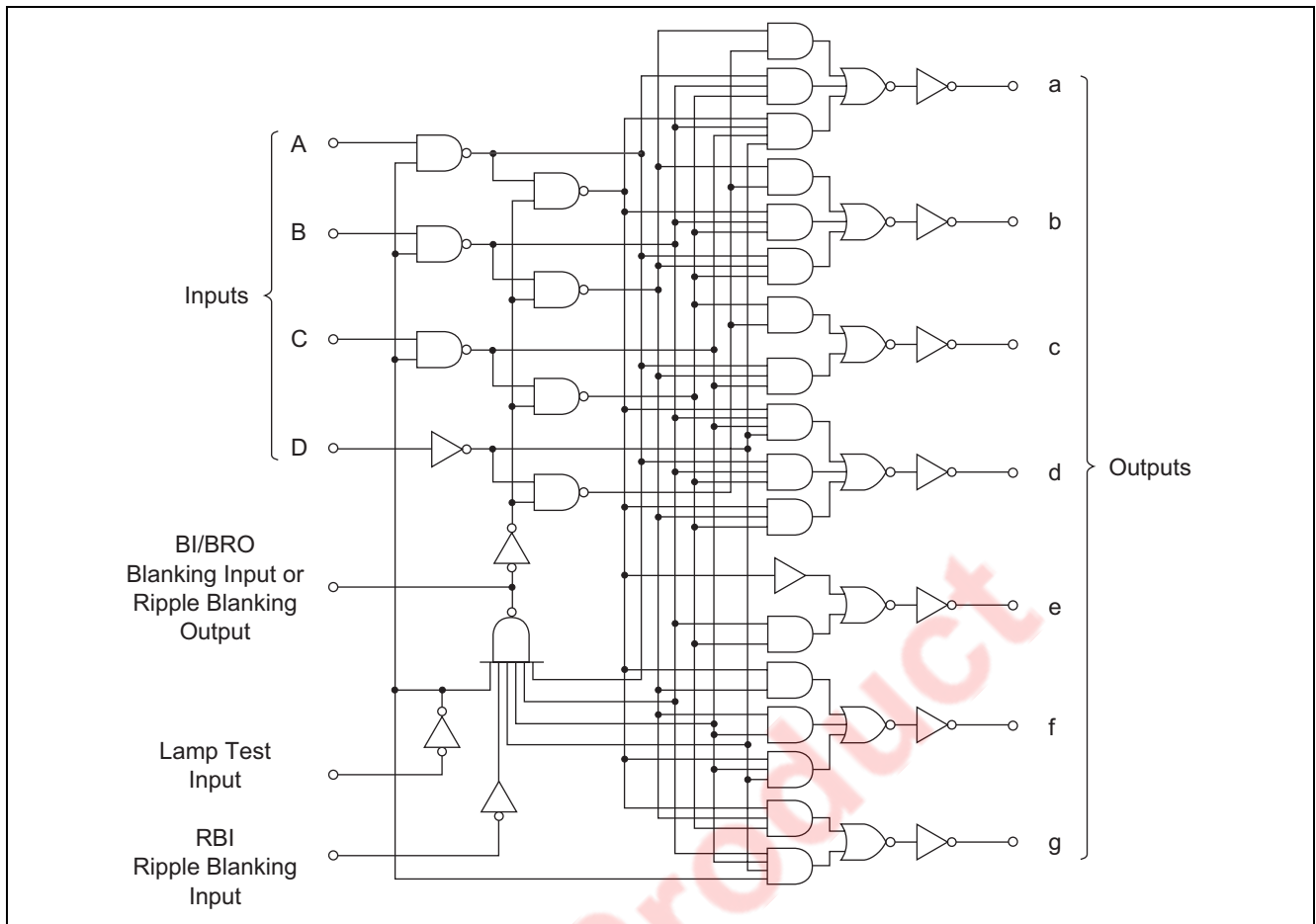
Function Table

Decimal or Function	Inputs						BI/ RBO	Outputs							Note
	LT	RBI	D	C	B	A		a	b	c	d	e	f	g	
0	H	H	L	L	L	L	H	ON	ON	ON	ON	ON	ON	OFF	1
1	H	X	L	L	L	H	H	OFF	ON	ON	OFF	OFF	OFF	OFF	
2	H	X	L	L	H	L	H	ON	ON	OFF	ON	ON	OFF	ON	
3	H	X	L	L	H	H	H	ON	ON	ON	ON	OFF	OFF	ON	
4	H	X	L	H	L	L	H	OFF	ON	ON	OFF	OFF	ON	ON	
5	H	X	L	H	L	H	H	ON	OFF	ON	ON	OFF	ON	ON	
6	H	X	L	H	H	L	H	ON	OFF	ON	ON	ON	ON	ON	
7	H	X	L	H	H	H	H	ON	ON	ON	OFF	OFF	OFF	OFF	
8	H	X	H	L	L	L	H	ON	ON	ON	ON	ON	ON	ON	
9	H	X	H	L	L	H	H	ON	ON	ON	ON	OFF	ON	ON	
10	H	X	H	L	H	L	H	OFF	OFF	OFF	ON	ON	OFF	ON	
11	H	X	H	L	H	H	H	OFF	OFF	ON	ON	OFF	OFF	ON	
12	H	X	H	H	L	L	H	OFF	ON	OFF	OFF	OFF	ON	ON	
13	H	X	H	H	L	H	H	ON	OFF	OFF	ON	OFF	ON	ON	
14	H	X	H	H	H	L	H	OFF	OFF	OFF	ON	ON	ON	ON	
15	H	X	H	H	H	H	H	OFF	OFF	OFF	OFF	OFF	OFF	OFF	
BI	X	X	X	X	X	X	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	2
RBI	H	L	L	L	L	L	L	OFF	OFF	OFF	OFF	OFF	OFF	OFF	3
LT	L	X	X	X	X	X	H	ON	ON	ON	ON	ON	ON	ON	4

H; high level, L; low level, X; irrelevant

- Notes:
1. The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.
 2. When a low logic level is applied directly to the blanking input (BI), all segment outputs are off regardless of the level of any other input.
 3. When ripple-blanking input (RBI) and inputs A, B, C, and D are a low level with the lamp test input high, all segment outputs go off and the ripple-blanking output (RBO) goes to a low level (response condition).
 4. When a blanking input ripple blanking input (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are on.

Block Diagram



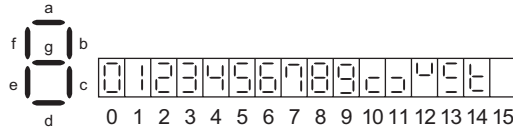
Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Output current ($t_w \leq 1\text{ms}$, duty cycle $\leq 10\%$)	$I_{O(\text{peak})}$	200	mA
Output current (off-state)	$I_{O(\text{off})}$	1	mA
Operating temperature	T_{opr}	-20 to +75	°C
Power dissipation	P_T	400	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item		Symbol	Min	Typ	Max	Unit
Supply voltage		V_{CC}	4.75	5.00	5.25	V
Operating temperature		T_{opr}	-20	25	75	°C
Output voltage	a to g	$V_{O(off)}$	—	—	15	V
Output current	a to g	$I_{O(on)}$	—	—	24	mA
	BI / RBO	I_{OH}	—	—	-50	μA
	BI / RBO	I_{OL}	—	—	3.2	mA



Electrical Characteristics

(Ta = -20 to +75 °C)

Item		Symbol	min.	typ.*	max.	Unit	Condition	
Input voltage		V_{IH}	2.0	—	—	V		
		V_{IL}	—	—	0.8	V		
Output voltage	BI/RBO	V_{OH}	2.4	—	—	V	$V_{CC} = 4.75\text{ V}$, $V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$, $I_{OH} = -50\text{ }\mu\text{A}$	
	BI/RBO	V_{OL}	—	—	0.4	V	$I_{OL} = 1.6\text{ mA}$	$V_{CC} = 4.75\text{ V}$, $V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$
			—	—	0.5		$I_{OL} = 3.2\text{ mA}$	
	Output current	a to g	$I_{O\text{ (off)}}$	—	—	250	μA	$V_{CC} = 5.25\text{ V}$, $V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$, $V_{O\text{ (off)}} = 15\text{ V}$
Output voltage	a to g	$V_{O\text{ (on)}}$	—	—	0.4	V	$I_{O\text{ (on)}} = 12\text{ mA}$	$V_{CC} = 5.25\text{ V}$, $V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$
			—	—	0.5		$I_{O\text{ (on)}} = 24\text{ mA}$	
Input current		I_{IH}	—	—	20	μA	$V_{CC} = 5.25\text{ V}$, $V_I = 2.7\text{ V}$	
	Except BI/RBO	I_{IL}	—	—	-0.4	mA	$V_{CC} = 5.25\text{ V}$, $V_I = 0.4\text{ V}$	
			—	—	-1.2			
			I_I	—	—	0.1	mA	$V_{CC} = 5.25\text{ V}$, $V_I = 7\text{ V}$
Short-circuit output current	BI/RBO	I_{OS}	-0.3	—	-2	mA	$V_{CC} = 5.25\text{ V}$	
Supply current**		I_{CC}	—	7	13	mA	$V_{CC} = 5.25\text{ V}$	
Input clamp voltage		V_{IK}	—	—	-1.5	V	$V_{CC} = 4.75\text{ V}$, $I_{IN} = -18\text{ mA}$	

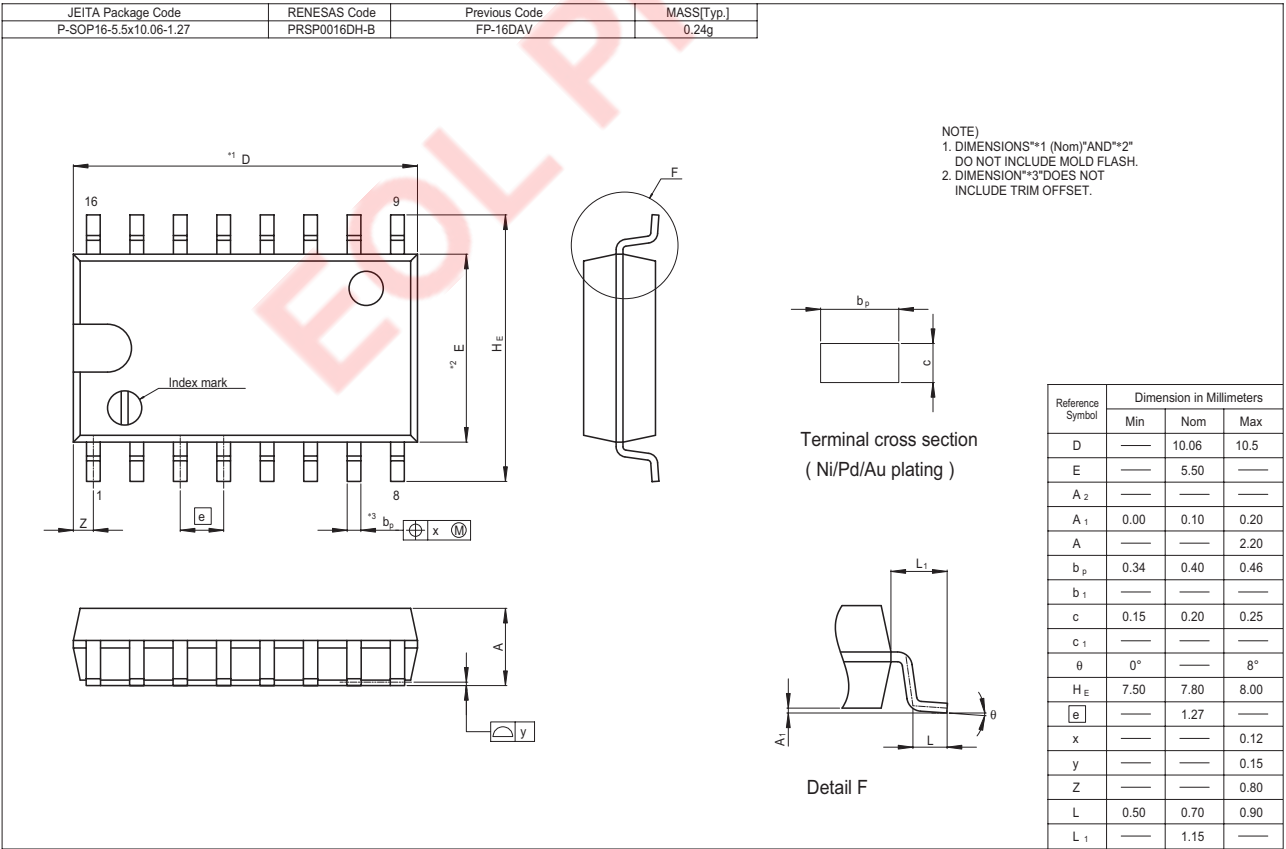
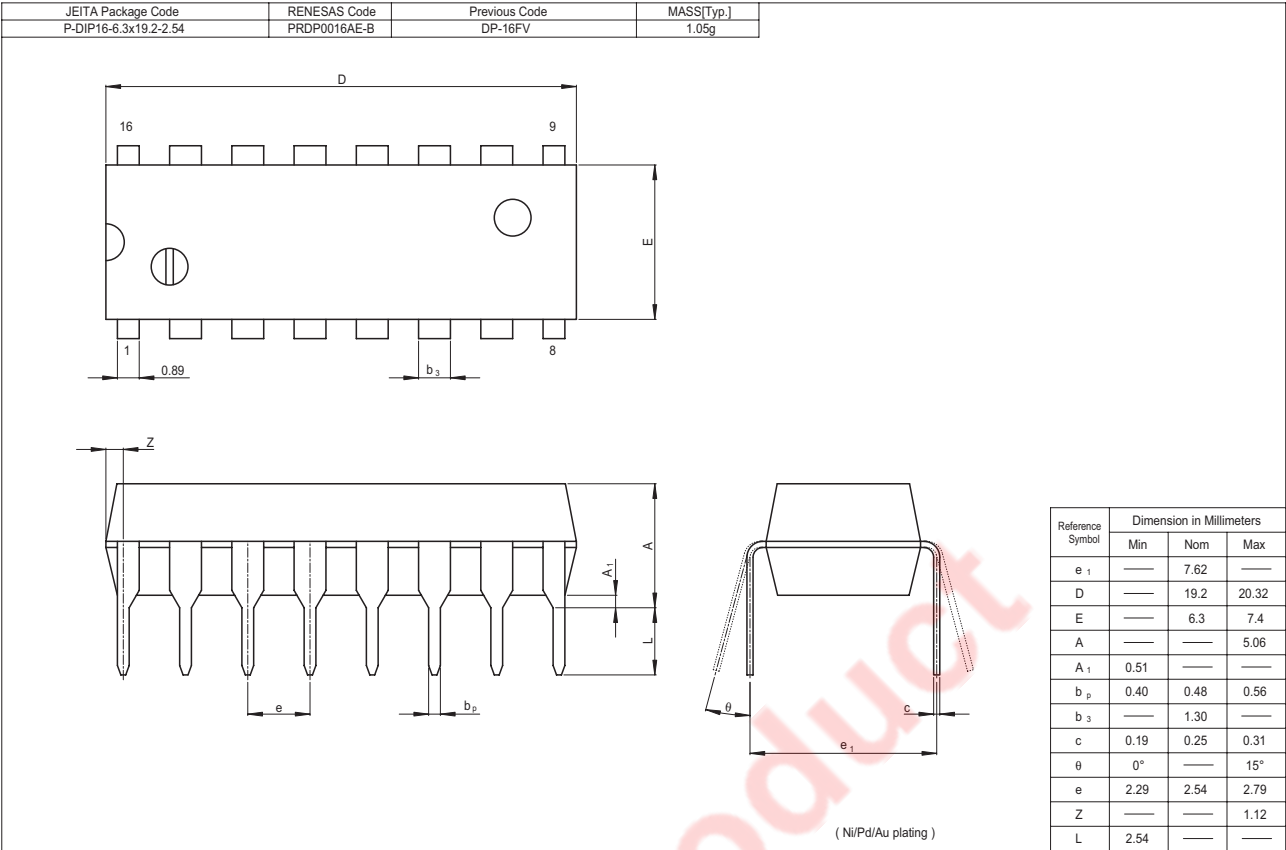
Notes: * $V_{CC} = 5\text{ V}$, $T_a = 25^\circ\text{C}$ ** I_{CC} is measured with all outputs open and all inputs at 4.5 V.

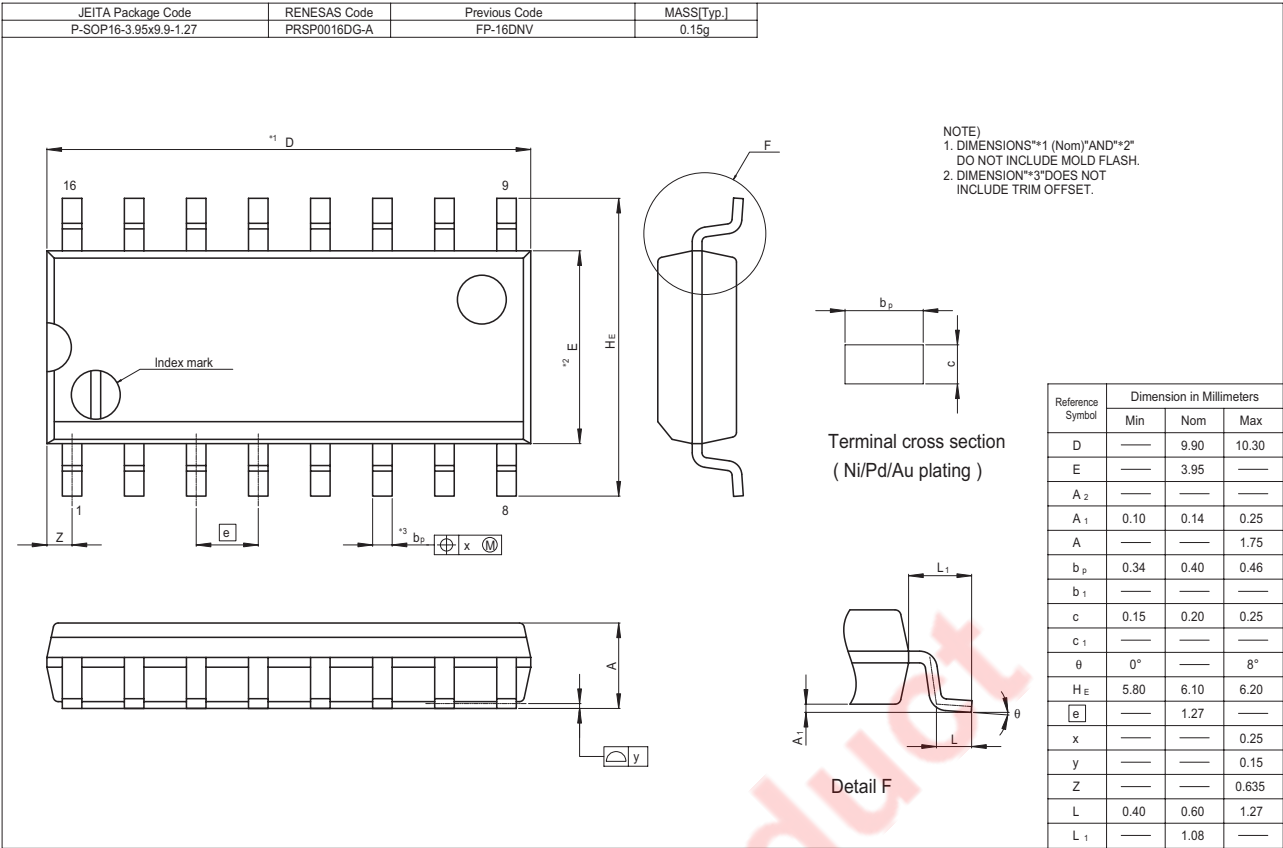
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

Item	Symbol	Input	min.	typ.	max.	Unit	Condition
Turn-on time	t_{on}	A	—	—	100	ns	$C_L = 15\text{ pF}$, $R_L = 665\text{ }\Omega$
		RBI	—	—	100		
Turn-off time	t_{off}	A	—	—	100	ns	
		RBI	—	—	100		

Package Dimensions





Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs!

1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors.
Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



RENESAS SALES OFFICES

<http://www.renesas.com>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A.
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology (Shanghai) Co., Ltd.

Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510